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# **Dual 1-of-4 Decoder/ Demultiplexer**

# **High-Performance Silicon-Gate CMOS**

The MC74HC139A is identical in pinout to the LS139. The device inputs are compatible with standard CMOS outputs; with pull-up resistors, they are compatible with LSTTL outputs.

This device consists of two independent 1-of-4 decoders, each of which decodes a two-bit Address to one-of-four active-low outputs. Active-low Selects are provided to facilitate the demultiplexing and cascading functions. The demultiplexing function is accomplished by using the Address inputs to select the desired device output, and utilizing the Select as a data input.

#### **Features**

- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS and TTL
- Operating Voltage Range: 2.0 to 6.0 V
- Low Input Current: 1.0 μA
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the Requirements Defined by JEDEC Standard No. 7 A
- Chip Complexity: 100 FETs or 25 Equivalent Gates
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant



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#### MARKING DIAGRAMS



PDIP-16 N SUFFIX CASE 648





SOIC-16 D SUFFIX CASE 751B





1

TSSOP-16 DT SUFFIX CASE 948F



A = Assembly Location

L, WL = Wafer Lot Y, YY = Year W, WW = Work Week G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

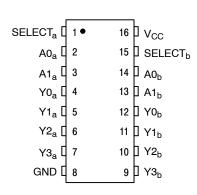


Figure 1. Pin Assignment

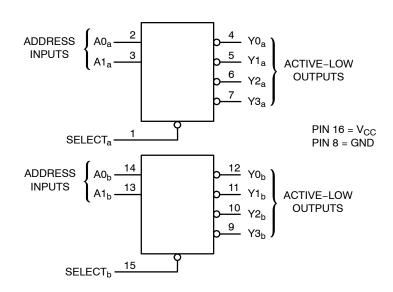


Figure 2. Logic Diagram

#### **FUNCTION TABLE**

| Inputs |    |    | Outputs |    |    |           |
|--------|----|----|---------|----|----|-----------|
| Select | A1 | Α0 | Y0      | Y1 | Y2 | <b>Y3</b> |
| Н      | Х  | Χ  | Н       | Н  | Н  | Н         |
| L      | L  | L  | L       | Н  | Н  | Н         |
| L      | L  | Н  | Н       | L  | Н  | Н         |
| L      | Н  | L  | Н       | Н  | L  | Н         |
| L      | Н  | Н  | Н       | Н  | Н  | L         |

X = don't care

#### **ORDERING INFORMATION**

| Device            | Package               | Shipping <sup>†</sup> |
|-------------------|-----------------------|-----------------------|
| MC74HC139ANG      | PDIP-16<br>(Pb-Free)  | 2000 Units / Box      |
| MC74HC139ADG      | SOIC-16<br>(Pb-Free)  | 48 Units / Rail       |
| MC74HC139ADR2G    | SOIC-16<br>(Pb-Free)  | 2500 / Tape & Reel    |
| MC74HC139ADTR2G   | TSSOP-16<br>(Pb-Free) | 2500 / Tape & Reel    |
| NLV74HC139ADR2G*  | SOIC-16<br>(Pb-Free)  | 2500 / Tape & Reel    |
| NLV74HC139ADTR2G* | TSSOP-16<br>(Pb-Free) | 2500 / Tape & Reel    |

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>\*</sup>NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable

#### **MAXIMUM RATINGS**

| Symbol               | Parame                                  | ter  | Value                        | Unit |
|----------------------|---|--|------------------------------|------|
| $V_{CC}$             | DC Supply Voltage                       | (Referenced to GND)  | -0.5 to +7.0                 | V    |
| V <sub>IN</sub>      | DC Input Voltage                        | (Referenced to GND)  | -1.5 to V <sub>CC</sub> +1.5 | V    |
| V <sub>OUT</sub>     | DC Output Voltage                       | (Referenced to GND) (Note 1)   | $-0.5$ to $V_{CC}$ + 0.5     | V    |
| I <sub>IN</sub>      | DC Input Current, per Pin               |  | ±20                          | mA   |
| I <sub>OUT</sub>     | DC Output Current, per Pin              |  | ± 25                         | mA   |
| I <sub>CC</sub>      | DC Supply Current, V <sub>CC</sub> Pin  |  | ±50                          | mA   |
| I <sub>GND</sub>     | DC Ground Current per Ground Pin        |  | ±50                          | mA   |
| T <sub>STG</sub>     | Storage Temperature Range               |  | -65 to +150                  | °C   |
| TL                   | Lead Temperature, 1 mm from Case for 10 | Seconds  | 260                          | °C   |
| TJ                   | Junction Temperature Under Bias         |  | + 150                        | °C   |
| $\theta_{\sf JA}$    | Thermal Resistance                      | PDIP<br>SOIC<br>TSSOP  | 78<br>112<br>148             | °C/W |
| P <sub>D</sub>       | Power Dissipation in Still Air at 85°C  | PDIP<br>SOIC<br>TSSOP  | 750<br>500<br>450            | mW   |
| MSL                  | Moisture Sensitivity                    |  | Level 1                      |      |
| F <sub>R</sub>       | Flammability Rating                     | Oxygen Index: 30% – 35%  | UL 94 V-0 @ 0.125 in         |      |
| V <sub>ESD</sub>     | ESD Withstand Voltage                   | Human Body Model (Note 2)<br>Machine Model (Note 3)<br>Charged Device Model (Note 4) | > 2000<br>> 200<br>> 1000    | V    |
| I <sub>LATCHUP</sub> | Latchup Performance Above               | V <sub>CC</sub> and Below GND at 85°C (Note 5)                                       | ±300                         | mA   |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- I<sub>O</sub> absolute maximum rating must be observed.
   Tested to EIA/JESD22-A114-A.
   Tested to EIA/JESD22-A115-A.

- Tested to JESD22-C101-A.
   Tested to EIA/JESD78.

#### **RECOMMENDED OPERATING CONDITIONS**

| Symbol                             | Parameter                                | Min   | Max         | Unit               |    |
|------------------------------------|--|---|-------------|--------------------|----|
| V <sub>CC</sub>                    | DC Supply Voltage                        | (Referenced to GND)   | 2.0         | 6.0                | V  |
| V <sub>IN</sub> , V <sub>OUT</sub> | DC Input Voltage, Output Voltage         | (Referenced to GND)   | 0           | V <sub>CC</sub>    | V  |
| T <sub>A</sub>                     | Operating Temperature, All Package Types |   | <b>- 55</b> | + 125              | °C |
| t <sub>r</sub> , t <sub>f</sub>    | Input Rise and Fall Time<br>(Figure 3)   | V <sub>CC</sub> = 2.0 V<br>V <sub>CC</sub> = 4.5 V<br>V <sub>CC</sub> = 6.0 V | 0<br>0<br>0 | 1000<br>500<br>400 | ns |

6. Unused inputs may not be left open. All inputs must be tied to a high-logic voltage level or a low-logic input voltage level.

#### DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

|                 |   |  | V <sub>CC</sub>   | Guaranteed Limit   |                    |                    |          |
|-----------------|---|--|-------------------|--------------------|--------------------|--------------------|----------|
| Symbol          | Parameter   | Test Conditions  | V                 | −55°C to 25°C      | ≤ <b>85</b> °C     | ≤125°C             | Unit     |
| V <sub>IH</sub> | Minimum High-Level Input<br>Voltage               | $V_{OUT}$ = 0.1 V or $V_{CC}$ - 0.1 V $ I_{OUT}  \le 20 \mu A$   | 2.0<br>4.5<br>6.0 | 1.5<br>3.15<br>4.2 | 1.5<br>3.15<br>4.2 | 1.5<br>3.15<br>4.2 | V        |
| V <sub>IL</sub> | Maximum Low-Level Input<br>Voltage                | $V_{OUT}$ = 0.1 V or $V_{CC}$ -0.1 V $ I_{OUT}  \le 20 \mu A$  | 2.0<br>4.5<br>6.0 | 0.5<br>1.35<br>1.8 | 0.5<br>1.35<br>1.8 | 0.5<br>1.35<br>1.8 | ٧        |
| V <sub>OH</sub> | Minimum High-Level Output<br>Voltage              | $V_{IN} = V_{IH} \text{ or } V_{IL}$<br>$ I_{OUT}  \le 20 \ \mu\text{A}$   | 2.0<br>4.5<br>6.0 | 1.9<br>4.4<br>5.9  | 1.9<br>4.4<br>5.9  | 1.9<br>4.4<br>5.9  | ٧        |
|                 |   | $V_{IN} = V_{IH} \text{ or } V_{IL} \qquad \begin{vmatrix} I_{OUT} \end{vmatrix} \le 4.0 \text{ m/} \\  I_{OUT}  \le 5.2 \text{ m/} \end{vmatrix}$ | A 4.5<br>A 6.0    | 3.98<br>5.48       | 3.84<br>5.34       | 3.70<br>5.20       |          |
| V <sub>OL</sub> | Maximum Low-Level Output<br>Voltage               | $V_{IN} = V_{IH} \text{ or } V_{IL}$<br>$ I_{OUT}  \le 20 \ \mu\text{A}$   | 2.0<br>4.5<br>6.0 | 0.1<br>0.1<br>0.1  | 0.1<br>0.1<br>0.1  | 0.1<br>0.1<br>0.1  | <b>V</b> |
|                 |   | $V_{IN} = V_{IH}$ or $V_{IL}$ $ I_{OUT}  \le 4.0 \text{ m/}$<br>$ I_{OUT}  \le 5.2 \text{ m/}$   | A 4.5<br>A 6.0    | 0.26<br>0.26       | 0.33<br>0.33       | 0.40<br>0.40       |          |
| I <sub>IN</sub> | Maximum Input Leakage<br>Current                  | V <sub>IN</sub> = V <sub>CC</sub> or GND   | 6.0               | ± 0.1              | ±1.0               | ±1.0               | μА       |
| I <sub>CC</sub> | Maximum Quiescent Supply<br>Current (per Package) | $V_{IN} = V_{CC}$ or GND $I_{OUT} = 0 \mu A$   | 6.0               | 4                  | 40                 | 160                | μА       |

### AC ELECTRICAL CHARACTERISTICS ( $C_L$ = 50 pF, Input $t_r$ = $t_f$ = 6.0 ns)

|  |  | V <sub>CC</sub>   | Guaranteed Limit |                 |                 |      |
|--|--|-------------------|------------------|-----------------|-----------------|------|
| Symbol                                 | Parameter  | V                 | −55°C to 25°C    | ≤ <b>85</b> °C  | ≤125°C          | Unit |
| t <sub>PLH</sub> ,<br>t <sub>PHL</sub> | Maximum Propagation Delay, Select to Output Y (Figures 1 and 3)  | 2.0<br>4.5<br>6.0 | 115<br>23<br>20  | 145<br>29<br>25 | 175<br>35<br>30 | ns   |
| t <sub>PLH</sub> ,<br>t <sub>PHL</sub> | Maximum Propagation Delay, Input A to Output Y (Figures 2 and 3) | 2.0<br>4.5<br>6.0 | 115<br>23<br>20  | 145<br>29<br>25 | 175<br>35<br>30 | ns   |
| t <sub>TLH</sub> ,<br>t <sub>THL</sub> | Maximum Output Transition Time, Any Output (Figures 1 and 3)     | 2.0<br>4.5<br>6.0 | 75<br>15<br>13   | 95<br>19<br>16  | 110<br>22<br>19 | ns   |
| C <sub>in</sub>                        | Maximum Input Capacitance  | -                 | 10               | 10              | 10              | pF   |

<sup>7.</sup> For propagation delays with loads other than 50 pF, and information on typical parametric values, see the ON Semiconductor High–Speed CMOS Data Book (DL129/D).

|                 |  | Typical @ 25°C, V <sub>CC</sub> = 5.0 V |    |
|-----------------|--|---|----|
| C <sub>PD</sub> | Power Dissipation Capacitance (Per Decoder) (Note 8) | 55                                      | pF |

<sup>8.</sup> Used to determine the no-load dynamic power consumption:  $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$ .

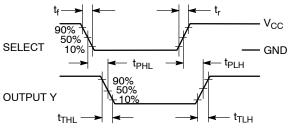


Figure 3. Switching Waveform

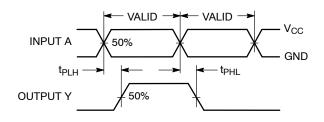
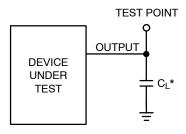


Figure 4. Switching Waveform



<sup>\*</sup> Includes all probe and jig capacitance

Figure 5. Test Circuit

#### **PIN DESCRIPTIONS**

#### **ADDRESS INPUTS**

#### A0<sub>a</sub>, A1<sub>a</sub>, A0<sub>b</sub>, A1<sub>b</sub> (Pins 2, 3, 14, 13)

Address inputs. These inputs, when the respective 1-of-4 decoder is enabled, determine which of its four active-low outputs is selected.

#### **CONTROL INPUTS**

#### Select<sub>a</sub>, Select<sub>b</sub> (Pins 1, 15)

Active-low select inputs. For a low level on this input, the outputs for that particular decoder follow the Address

inputs. A high level on this input forces all outputs to a high level.

#### **OUTPUTS**

Active-low outputs. These outputs assume a low level when addressed and the appropriate Select input is active. These outputs remain high when not addressed or the appropriate Select input is inactive.

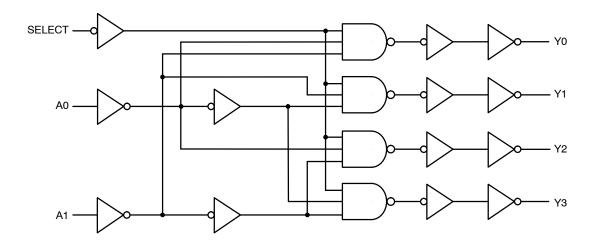
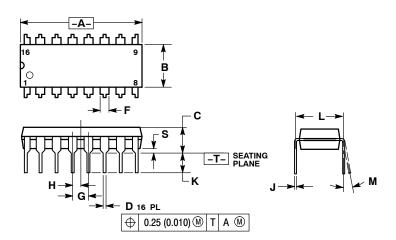


Figure 6. Expanded Logic Diagram (1/2 of Device)

#### **PACKAGE DIMENSIONS**

PDIP-16 CASE 648-08 ISSUE T

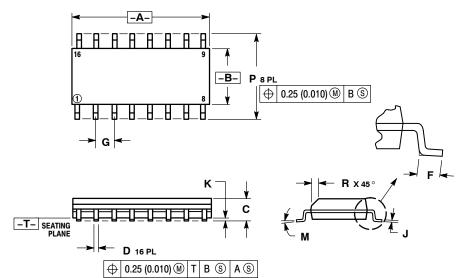


- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
  5. ROUNDED CORNERS OPTIONAL.

|     | INC   | HES   | MILLIN | IETERS |
|-----|-------|-------|--------|--------|
| DIM | MIN   | MAX   | MIN    | MAX    |
| Α   | 0.740 | 0.770 | 18.80  | 19.55  |
| В   | 0.250 | 0.270 | 6.35   | 6.85   |
| С   | 0.145 | 0.175 | 3.69   | 4.44   |
| D   | 0.015 | 0.021 | 0.39   | 0.53   |
| F   | 0.040 | 0.70  | 1.02   | 1.77   |
| G   | 0.100 | BSC   | 2.54   | BSC    |
| Н   | 0.050 | BSC   | 1.27   | BSC    |
| J   | 0.008 | 0.015 | 0.21   | 0.38   |
| K   | 0.110 | 0.130 | 2.80   | 3.30   |
| L   | 0.295 | 0.305 | 7.50   | 7.74   |
| M   | 0°    | 10 °  | 0°     | 10 °   |
| S   | 0.020 | 0.040 | 0.51   | 1.01   |

#### **PACKAGE DIMENSIONS**

SOIC-16 CASE 751B-05 ISSUE K



#### NOTES:

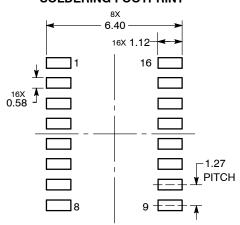
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
  DIMENSIONS A AND B DO NOT INCLUDE MOLD
  PROTRUSION. 3.
- PHOLINUSION.

  MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

  DIMENSION D DOES NOT INCLUDE DAMBAR
  PROTRUSION. ALLOWABLE DAMBAR PROTRUSION
  SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D
  DIMENSION AT MAXIMUM MATERIAL CONDITION.

|     | MILLIN | IETERS   | INCHES |       |  |
|-----|--------|----------|--------|-------|--|
| DIM | MIN    | MAX      | MIN    | MAX   |  |
| Α   | 9.80   | 10.00    | 0.386  | 0.393 |  |
| В   | 3.80   | 4.00     | 0.150  | 0.157 |  |
| С   | 1.35   | 1.75     | 0.054  | 0.068 |  |
| D   | 0.35   | 0.49     | 0.014  | 0.019 |  |
| F   | 0.40   | 1.25     | 0.016  | 0.049 |  |
| G   | 1.27   | 1.27 BSC |        | BSC   |  |
| J   | 0.19   | 0.25     | 0.008  | 0.009 |  |
| K   | 0.10   | 0.25     | 0.004  | 0.009 |  |
| M   | 0°     | 7°       | 0 °    | 7°    |  |
| Р   | 5.80   | 6.20     | 0.229  | 0.244 |  |
| R   | 0.25   | 0.50     | 0.010  | 0.019 |  |

#### **SOLDERING FOOTPRINT\***

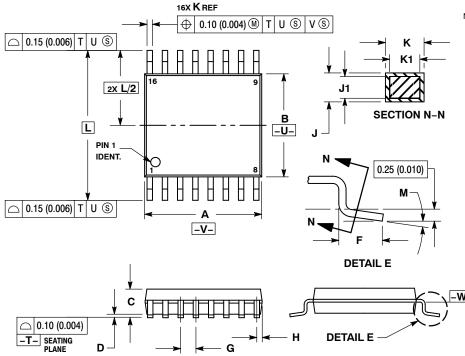


DIMENSIONS: MILLIMETERS

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### **PACKAGE DIMENSIONS**

#### TSSOP-16 CASE 948F-01 **ISSUE B**



#### NOTES:

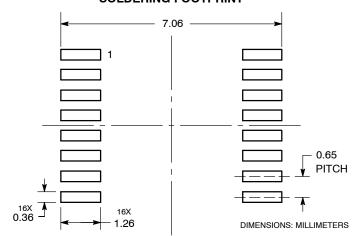
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER.
- 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS.
- FLASH. PROTRUSIONS OR GATE BURRS.
  MOLD FLASH OR GATE BURRS SHALL NOT
  EXCEED 0.15 (0.006) PER SIDE.

  4. DIMENSION B DOES NOT INCLUDE
  INTERLEAD FLASH OR PROTRUSION.
  INTERLEAD FLASH OR PROTRUSION SHALL
  NOT EXCEED 0.25 (0.010) PER SIDE.

  5. DIMENSION K DOES NOT INCLUDE
  DAMBAR PROTRUSION, ALLOWABLE
  DAMBAR PROTRUSION, SLALL BE COE
- DAMBAH PHOI HUSION. ALLOWABLE
  DAMBAH PROTRUSION SHALL BE 0.08
  (0.003) TOTAL IN EXCESS OF THE K
  DIMENSION AT MAXIMUM MATERIAL
  CONDITION.
  6. TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.
  7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

|     | MILLIMETERS |      | INC       | HES   |  |
|-----|-------------|------|-----------|-------|--|
| DIM | MIN         | MAX  | MIN       | MAX   |  |
| Α   | 4.90        | 5.10 | 0.193     | 0.200 |  |
| В   | 4.30        | 4.50 | 0.169     | 0.177 |  |
| С   |             | 1.20 |           | 0.047 |  |
| D   | 0.05        | 0.15 | 0.002     | 0.006 |  |
| F   | 0.50        | 0.75 | 0.020     | 0.030 |  |
| G   | 0.65 BSC    |      | 0.026     | BSC   |  |
| Н   | 0.18        | 0.28 | 0.007     | 0.011 |  |
| L   | 0.09        | 0.20 | 0.004     | 0.008 |  |
| J1  | 0.09        | 0.16 | 0.004     | 0.006 |  |
| K   | 0.19        | 0.30 | 0.007     | 0.012 |  |
| K1  | 0.19        | 0.25 | 0.007     | 0.010 |  |
| L   | 6.40        | BSC  | 0.252 BSC |       |  |
| M   | 0°          | 8°   | 0°        | 8 °   |  |

#### **SOLDERING FOOTPRINT**



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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5962-8607001EA NTE74LS247 5962-8756601EA SN74LS148N 8CA3052APGGI8 TC74VHC138F(EL,K,F PI3B3251LE PI3B3251QE
NTE4028B NTE4514B NTE4515B NTE4543B NTE4547B NTE74LS249 NLV74HC4851AMNTWG MC74LVX257DG
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